

# Junjian Chi

chijunjian@gmail.com | LinkedIn | GitHub | Google Scholar | Chi's Website

## EDUCATION

|   |                              |
|---|------------------------------|
| <b>University of Cambridge</b><br><i>MRes in Sensor Technologies and Applications</i>                         | 2025 – 2026<br>Cambridge, UK |
| <b>University College London</b><br><i>BEng in Electrical and Electronic Engineering, First-Class Honours</i> | 2022 – 2025<br>London, UK    |

## PUBLICATIONS

- [1] J. Chi, Z. Zhang, Q. Zhang, A. Demosthenous, and Y. Wu, "Multimodal Smart Insole with Crossbar Crosstalk Compensation for Fall-Risk Prediction," Accepted by IEEE Int. Symp. Circuits and Systems. (ISCAS 2026, Poster)
- [2] J. Chi, Q. Zhang, Z. Zhang, A. Demosthenous, and Y. Wu, "High-Resolution Plantar Pressure Insole System for Enhanced Lower Body Biomechanical Analysis," Published to IEEE Int. Symp. Circuits Syst. (ISCAS 2025, Lecture)
- [3] J. Chi, Q. Zhang, Z. Zhang, A. Demosthenous, and Y. Wu, "Live Demonstration: A High-Resolution Plantar Insole System for Lower Body Estimation," Published to IEEE Int. Symp. Circuits Syst. (ISCAS 2025, Poster)
- [4] J. Chi, S. Sivasubramani, J. Ghosh, V. Georgiev, R. Shafik, and T. Prodromakis, "Machine Learning for Skyrmion Dynamics under Multi-physics Coupling," Published to UK AI Research Symposium. (UKAIRS 2025, Poster)

## RESEARCH & INDUSTRY EXPERIENCE

|   |  |
|---|--|
| <b>Google DeepMind Research Ready Internship</b><br><i>Project: Integrating Multi-Physics Modelling and Machine Learning in Spintronics</i>   | Jun. 2025 – Jul. 2025<br>University of Edinburgh, UK   |
| – Sweep micromagnetic simulations of skyrmion dynamics on COMSOL for 10K+ dataset generation.<br>– Perform feature engineering and fine-tune optimum classifier models for dynamic behavior analysis.                                 |  |
| <b>Rosetrees Funded Research Assistant</b><br><i>Project: Multimodal Insole System for Lower-body Clinical Enhancement</i>  | Oct. 2024 – Jul. 2025<br>University College London, UK |
| – Fabricate an insole-shaped flexible PCB with 253 velostat resistive pressure sensors and inertial motion unit.<br>– Design a multimodal 3D CNN + Transformer to predict joint positions and probability of falling at 91% accuracy. |  |
| <b>Qualcomm Funded Summer Internship</b><br><i>Project: Circuit and System for Biomedical Applications, Robotics and HMI</i>  | Aug. 2024 – Sep. 2024<br>University College London, UK |
| – Design a 4-layer PCB of customized analogue front end for sensor linearity compensation with ESP32-wroom chip.<br>– Utilize FreeRTOS for ADC DMA readout and Wi-Fi AP transmission, build test platform for insole SoC.             |  |
| <b>UROP Research Assistant</b><br><i>Project: Wearable Multimodal EMG/Ultrasound Sleeve for Prosthetic Control</i>  | Jun. 2024 – Aug. 2024<br>Imperial College London, UK   |
| – Model and fabricate a wearable flexible silicon armband for EMG and ultrasound sensors placement.<br>– Develop embedded system to collect and filter EMG signals from 16-channel electrodes.  |  |

## PROJECTS & COMPETITIONS

|   |                       |
|---|-----------------------|
| <b>IEEE CASS Student Design Competition</b>   <i>Team Leader</i>  | Dec. 2023 – Mar. 2024 |
| – Low-cost ingestible biosensor-pill for colon-targeted drug delivery, awarded <b>1st Place</b> in UK & Ireland Chapter.        |                       |
| <b>Single-Cycle RISC-V CPU Design</b>   <i>Undergrad Coursework</i>   | Feb. 2025             |
| – Implemented a 32-bit Single-Cycle RISC-V CPU and verified functionality with testbenches using System Verilog.                |                       |
| <b>FPGA Audio Descrambler</b>   <i>Undergrad Coursework</i>   | Mar. 2024             |
| – Configured PLLs for clock synchronization and applied bandstop filtering/frequency mixing for signal descrambling in Quartus. |                       |

## TECHNICAL SKILLS

**Languages:** Python, C, C++, System Verilog, MATLAB  
**Software:** Git, Linux, FreeRTOS, Quartus, Altium Designer, COMSOL, Unity, Fusion 360, Blender  
**Hardware:** PCB Layout Design, Embedded Systems (ESP32, STM32, Jetson), FPGA, 3D Printing, Soldering